

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHO-FAN HSIEH	06/04/2015
CHIH-HUA CHEN	06/04/2015
HUNG-SEN WU	06/04/2015
TENG-CHUN WU	06/04/2015
MING-HAN LIAO	06/04/2015
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14737152
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DATE SIGNED:	06/12/2015
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, Cho-Fan HSIEH, Chih-Hua CHEN, Hung-Sen WU, Teng-Chun WU and Ming-Han LIAO hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: MAGNETIC CAPACITOR STRUCTURES

Filed: June 11, 2015 Serial No. 14/737,152

Executed on: 2015/6/4

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Full name of sole or first inventor: Cho-Fan HSIEH	
Inventor's signature: Cho Fan Hsieh	Date: 2015/6/4

Full name of second inventor: Chih-Hua CHEN	
Inventor's signature: Chih-Hua Chen	Date: 2015/06/04

Full name of third inventor: Hung-Sen WU	
Inventor's signature: <i>Hung-Sen Wu</i>	Date: <i>2015/06/04</i>

Full name of fourth inventor: Teng-Chun WU	
Inventor's signature: <i>Teng Chun Wu</i>	Date: <i>2015/06/04</i>

Full name of fifth inventor: Ming-Han LIAO	
Inventor's signature: <i>Ming-Han Liao</i>	Date: <i>2015/06/09</i>